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Reliability, Packaging, Testing, and Characterization of MEMS/MOEMS and Nanodevices IX

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Contents

vii *Conference Committee*

ix *Introduction*

xi *Emerging research in micro and nano systems: opportunities and challenges for societal impact (Plenary Paper) [7593-201]*
Y. B. Gianchandani, Univ. of Michigan (United States)

xix *MEMS technologies for artificial retinas (Plenary Paper) [7594-202]*
W. Mokwa, RWTH Aachen Univ. (Germany)

xxxiii *Shaping light: MOEMS deformable mirrors for microscopes and telescopes (Plenary Paper) [7595-203]*
T. Bifano, Boston Univ. Photonics Ctr. (United States)

SESSION 1 MEMS PACKAGING: HERMETICITY CHARACTERIZATION

7592 02 **Nanoengineered surfaces for microfluidic-based thermal management devices (Invited Paper)** [7592-01]
E. N. Wang, R. Xiao, K.-H. Chu, Massachusetts Institute of Technology (United States)

7592 03 **A new method for hermeticity testing of wafer-level packaging** [7592-02]
D. Lellouchi, J. Dhennin, NOVA MEMS (France); X. Lafontan, INTESENS (France); D. Veyrie, CNES (France); A. Broue, NOVA MEMS (France) and LAAS, CNRS, Univ. of Toulouse (France); J.-F. Le Neal, LAAS, CNRS, Univ. of Toulouse (France) and Esterline Advanced Sensors (France); F. Pressecq, CNES (France)

7592 04 **Pressure sensing in vacuum hermetic micropackaging for MOEMS-MEMS** [7592-03]
M. M. Sisto, S. García-Blanco, L. Le Noc, B. Tremblay, Y. Desroches, J.-S. Caron, F. Provencal, F. Picard, Institut National d'Optique (Canada)

7592 05 **Wafer-level vacuum/hermetic packaging technologies for MEMS** [7592-04]
S.-H. Lee, J. Mitchell, Univ. of Michigan (United States) and ePack, Inc. (United States); W. Welch, Intek, Inc. (United States); S. Lee, Univ. of Michigan (United States) and ePack, Inc. (United States); K. Najafi, Univ. of Michigan (United States)

7592 06 **Characterization of polymeric getter materials for MEMS/MOEMS and other microelectronic package service** [7592-05]
R. C. Kullberg, B. L. Phillip, Vacuum Energy, Inc. (United States)

7592 07 **Hermetic vacuum sealing of MEMS devices containing organic components** [7592-06]
G. B. Tepolt, M. J. Mescher, J. J. LeBlanc, The Charles Stark Draper Lab., Inc. (United States); R. Lutwak, Symmetricom, Inc. (United States); M. Varghese, MEMSIC, Inc. (United States)

SESSION 2 RELIABILITY AND RF MEMS

7592 08 **Predicting reliability of silicon MEMS (Invited Paper)** [7592-07]
A. M. Fitzgerald, D. M. Pierce, B. Zeyen, A.M. Fitzgerald & Associates, LLC (United States)

7592 09 **Stability experiments on MEMS aluminum nitride RF resonators** [7592-08]
D. M. Tanner, R. H. Olsson III, T. B. Parson, S. M. Crouch, J. A. Walraven, J. A. Ohlhausen, Sandia National Labs. (United States)

7592 0A **Characterization of Au/Au, Au/Ru, and Ru/Ru ohmic contacts in MEMS switches improved by a novel methodology** [7592-09]
A. Broue, NOVA MEMS (France) and LAAS, CNRS, Univ. de Toulouse (France); J. Dhennin, NOVA MEMS (France); F. Courtade, CNES (France); C. Dieppedale, CEA-LETI (France); P. Pons, LAAS, CNRS, Univ. de Toulouse (France); X. Lafontan, NOVA MEMS (France) and INTESENS (France); R. Plana, LAAS, CNRS, Univ. de Toulouse (France)

7592 0B **Novel test fixture for collecting microswitch reliability data** [7592-10]
T. A. Edelmann, R. A. Coutu, Jr., L. A. Starman, Air Force Institute of Technology (United States)

7592 0C **Reliability study of a MEMS array under varying temperature and humidity conditions** [7592-11]
G. Sivakumar, R. Ranganathan, R. Gale, T. Dallas, Texas Tech Univ. (United States)

SESSION 3 PACKAGING AND MEMS RELIABILITY

7592 0D **The effects of plasma pretreatment and storage time on silicon fusion bonding (Invited Paper)** [7592-12]
C. B. O'Neal, J. Soman, Louisiana Tech Univ. (United States)

7592 0E **Lifetime estimation and reliability study of electrothermal MEMS actuators** [7592-13]
G. Sivakumar, Texas Tech Univ. (United States); S. Johns, Baylor Univ. (United States); J. A. Nava, Angelo State Univ. (United States); T. Dallas, Texas Tech Univ. (United States)

7592 0F **Reliability assessment of ceramic column grid array (CCGA717) interconnect packages under extreme temperatures for space applications (-185°C to +125°C)** [7592-14]
R. Ramesham, Jet Propulsion Lab. (United States)

7592 0G **Packaged bulk micromachined triglyceride biosensor** [7592-15]
S. V. Mohanasundaram, S. Mercy, P. V. Harikrishna, K. Rani, E. Bhattacharya, A. Chadha, Indian Institute of Technology Madras (India)

7592 0H **MEMS/microfluidics packaging without heating (Invited Paper)** [7592-16]
M. R. Howlader, McMaster Univ. (Canada)

7592 0I **Use of conductive adhesive for MEMS interconnection in military fuze applications** [7592-17]
J. Gakkestad, P. Dalsjo, Norwegian Defence Research Establishment (Norway); H. Kristiansen, Conpart AS (Norway); R. Johannessen, M. M. V. Taklo, SINTEF ICT (Norway)

SESSION 4 MEMS TESTING AND INSPECTION

7592 0J **Modeling time-dependent dielectric breakdown with and without barriers (Invited Paper)** [7592-18]
J. L. Plawsky, W. N. Gill, R. S. Achanta, Rensselaer Polytechnic Institute (United States)

7592 0K **Remotely accessible laboratory for MEMS testing** [7592-19]
G. Sivakumar, M. Mulsow, A. Melinger, S. Lacouture, T. E. Dallas, Texas Tech Univ. (United States)

7592 0L **Optical inspection of MOEMS devices using a configurable and suitable for production image processing system** [7592-20]
M. Scholles, M. Grafe, P. Miskowiec, V. Bock, H. Schenk, Fraunhofer Institute for Photonic Microsystems (Germany)

7592 0M **Low-cost system for testing MEMS for research and educational applications** [7592-21]
G. Ramirez, G. Sivakumar, S. Lacouture, T. Dallas, Texas Tech Univ. (United States)

SESSION 5 MEMS APPLICATIONS

7592 0N **Engineered nanowires, carbon nanotubes and graphene for sensors, actuators and electronics (Invited Paper)** [7592-22]
E. H. Yang, Stevens Institute of Technology (United States)

7592 0O **Optimal design of SAW-based gyroscope to improve sensitivity** [7592-23]
H. Oh, S. Yang, K. Lee, Ajou Univ. (Korea, Republic of)

7592 0P **Temperature measurement on MOEMS micromirror plates under illumination** [7592-24]
I. Wullinger, D. Rudloff, K. Lukat, P. Dürr, M. Krellmann, D. Kunze, A. Narayana Samy, U. Dauderstädt, M. Wagner, Fraunhofer Institute for Photonic Microsystems (Germany)

7592 0Q **Development and testing of a multi-level chevron actuator based positioning system** [7592-25]
S. Rawool, G. Sivakumar, J. Hendriske, D. Buscarello, Texas Tech Univ. (United States); I. Purushothaman, Arizona State Univ. (United States); T. E. Dallas, Texas Tech Univ. (United States)

7592 0R **Development of a microlens array (MLA) for maskless photolithography application** [7592-26]
M. Nam, H. Oh, G. Kim, S. Yang, K. Lee, Ajou Univ. (Korea, Republic of)

7592 0S **A 2-DOF MEMS positioning system** [7592-27]
G. Sivakumar, Texas Tech Univ. (United States); J. Mathews, Angelo State Univ. (United States); T. E. Dallas, Texas Tech Univ. (United States)

7592 0T **The influence of the arrangement and spacing of CNT column array on the characteristic of field emission** [7592-28]
K. Han, D. Jun, N. T. Hong, S. Lee, S. Yang, Ajou Univ. (Korea, Republic of)

7592 0U **Self-aligned maskless process for etching cavities in SOI wafers to enhance the quality factor of MEMS resonators** [7592-29]
W. Mohammad, V. Kaajakari, Louisiana Tech Univ. (United States)

SESSION 6 MECHANICAL PROPERTIES

7592 0V **Thermal microactuator performance as a function of mechanical stress** [7592-30]
L. M. Phinney, M. A. Spletzer, M. S. Baker, J. R. Serrano, Sandia National Labs. (United States)

7592 0W **Mitigating the irreversible deformation with pressure in silicon/porous silicon composite membranes** [7592-31]
L. Sujatha, Rajalakshmi Engineering College (India); R. Goswami, E. Bhattacharya, Indian Institute of Technology Madras (India)

7592 0X **Investigation into metamaterial structures operating at terahertz wavelength** [7592-32]
D. Langley, R. A. Coutu, Jr., L. A. Starman, M. A. Marciniak, Air Force Institute of Technology (United States)

POSTER SESSION

7592 0Z **Performance and reliability assessment of a dielectric charging guard in MEMS optical switch systems** [7592-36]
P. Zhang, E. Carr, D. Keebaugh, K. Chau, Glimmerglass Networks, Inc. (United States)

Author Index

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1 MEMS Packaging: Hermeticity Characterization
Rajeshuni Ramesham, Jet Propulsion Laboratory (United States)

2 Reliability and RF MEMS
Leslie M. Phinney, Sandia National Laboratories (United States)

3 Packaging and MEMS Reliability
Sonia García-Blanco, Institut National d'Optique (Canada)

4 MEMS Testing and Inspection
Richard C. Kullberg, Vacuum Energy, Inc. (United States)

5 MEMS Applications
Danelle M. Tanner, Sandia National Laboratories (United States)
Allyson L. Hartzell, Boston Micromachines Corporation (United States)

6 Mechanical Properties
Alissa M. Fitzgerald, A.M. Fitzgerald & Associates, LLC (United States)

Introduction

The reliability, packaging, testing, and characterization of MEMS/MOEMS are of paramount importance to the commercialization of these advanced and useful emerging technologies. Contributors to this conference attend from around the world, making it the premier international reliability conference for MEMS/MOEMS. The main objective of this conference is to provide a technical forum for in-depth investigations and interdisciplinary discussions involving reliability, packaging, testing, and characterization of MEMS/MOEMS. The response to the call for papers has been incredible over the years and technically rewarding to the MEMS/MOEMS and associated communities.

The Reliability, Packaging, Testing, and Characterization of MEMS/MOEMS and Nanodevices conference is sponsored by SPIE, and was organized as a part of Photonics West 2010. SPIE is the leading international forum for presentation of the latest developments associated with MEMS and MOEMS including reliability, testing, packaging, materials, surfaces, and characterization. Our conference was part of the Devices/Applications/Reliability symposium track and education program on MOEMS-MEMS held 24–29January 2010 at Moscone Center, San Francisco, California, USA. This conference has been held for over 10 consecutive years in various forms through the SPIE.

In preparing for the conference, 36 high-quality papers were received from various countries. This year six sessions covered MEMS Packaging: Hermeticity Characterization, Reliability and RF MEMS, Packaging and MEMS Reliability, MEMS Testing and Inspection, MEMS Applications, and Mechanical Properties of materials of MEMS. Our final technical program had three plenary speakers and six invited/keynote speakers from various reputed laboratories around the country and the globe.

We would like to personally thank Dr. Leslie Phinney, Dr. Danelle Tanner, Dr. Sonia García-Blanco, Dr. Allyson Hartzell, Ms. Alyssa M. Fitzgerald, and Dr. Thomas Suleski and Dr. Herald Schenk (symposium chair and cochair), as well as the SPIE staff for their unstinted timely support and encouragement. Finally, we would like to thank all the session chairs and cochairs, and the program committee members for their support in organizing this conference successfully and reviewing the abstract and proceedings articles. We thank all the participants and everyone who participated in this conference.

Richard C. Kullberg
Rajeshuni Ramesham